

# Description Guide

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### **Hardware**

**July 2020**

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## Preface

This guide gives a general overview of the server.

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**See** The Bull support web site for the most up-to-date product information, documentation, firmware updates, software fixes and service offers:  
<http://support.bull.com>

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## Intended Readers

This guide is intended for administrators and operators.

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## **Regulatory Declarations and Disclaimers**

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### **Safety Compliance Statement**

We hereby certify that this product is in compliance with:

#### **UE Certification**

Low voltage directive 2014/35/UE : Standard EN 60950-1

---

### **Electromagnetic Compatibility Statement**

This product is in conformity with the protection requirements of the following directives:

#### **European Community (UE) Certification**

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# Safety Notices

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**Important** Read the safety notices before undertaking any procedures described in the documentation.

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All safety notices used in the documentation are listed in the Multilingual Safety Notices Guide, 86 X1 12FL and are classified by severity:

**D0xx**  **DANGER**  
**D0xx**  
**A *Danger* notice indicates the presence of a hazard that has the potential of causing death or serious personal injury.**

**C0xx**  **CAUTION**  
**C0xx**  
**A *Caution* notice indicates the presence of a hazard that has the potential of causing moderate or minor personal injury.**

**W0xx**  **WARNING**  
**W0xx**  
**A *Warning* notice indicates an action that could cause damage to a program, device, system, or data.**

Each safety notices is prefixed with a unique identification number. This can be used to locate the corresponding translated version in the Multilingual Safety Notices Guide, 86 X1 12FL.



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## Chapter 1. Related publications

This list is not exhaustive. Useful documentation is supplied on the Resource & Documentation DVD(s) delivered with the system. You are strongly advised to refer carefully to this documentation before proceeding to configure, use, maintain, or update your system.

### Portfolio

- BullSequana Edge Customer Documentation Set, 86 AP 63PA  
contains all the customer documentation relative to the BullSequana Edge server.
- BullSequana Edge Field Documentation Set, 86 AP 64PA  
contains all the field documentation relative to the BullSequana Edge server.

### Read me First

- Resource and Documentation DVD  
contains the tools and documentation required to configure, operate and maintain the system.
- Generic Site Preparation Guide, 86 A1 85FP  
explains how to prepare a Data Processing Center for Bull Systems, in compliance with the standards in force. This guide is intended for use by all personnel and trade representatives involved in the site preparation process.
- Atos Servers Multilingual Safety Notices Guide, 86 X1 12FL  
lists, in different languages, the notices referenced in the documentation procedures.
- BullSequana Edge Description Guide, 86 A1 65FR  
gives a general overview of the server. This guide is intended for use by administrators and operators.

### Installation

- BullSequana Edge Installation Guide, 86 A1 67FR  
explains how to install the server. This guide is intended for use by qualified personnel in charge of installation.

### Operation

- BullSequana Edge Server Hardware Console Reference Guide, 86 A1 05FS  
explains how to use the BullSequana Edge hardware console. This guide is intended for use by system administrators and operators.
- BullSequana Edge Management Console User's Guide, 86 A1 99FR  
explains how to use the BullSequana Edge management console. This guide is intended for use by system administrators and operators.
- BullSequana Edge Getting Started Guide, 86 A1 07FS  
explains how to connect, configure, and boot the server. Some basic operations are also described.

## Maintenance

- BullSequana Edge Customer Service Guide, 86 A1 93FR explains how to replace the Customer Replaceable Units (CRU). This guide is intended for use by system administrators and operators.
- BullSequana Edge Field Service Guide, 86 A7 94FR explains how to replace the Field Replaceable Units (FRU). This guide is intended for use by qualified personnel.

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## Chapter 2. BullSequana Edge description

### 2.1. Overview

BullSequana Edge servers are based upon the MI (Machine Intelligence) architecture. They exploit the Intel ® Xeon ® platform, Skylake-D processor.

BullSequana Edge servers are designed to be modular, easy to maintain, and to support video security and digital signage verticals developed with the machine intelligence program. They are compact devices that can be installed in a closet or in an overhead location.

Each BullSequana Edge module is 2U high and includes one processor that can support up to four memory modules. There are two PCIe slots (two x16 generation 3) and two mini PCIe slots.

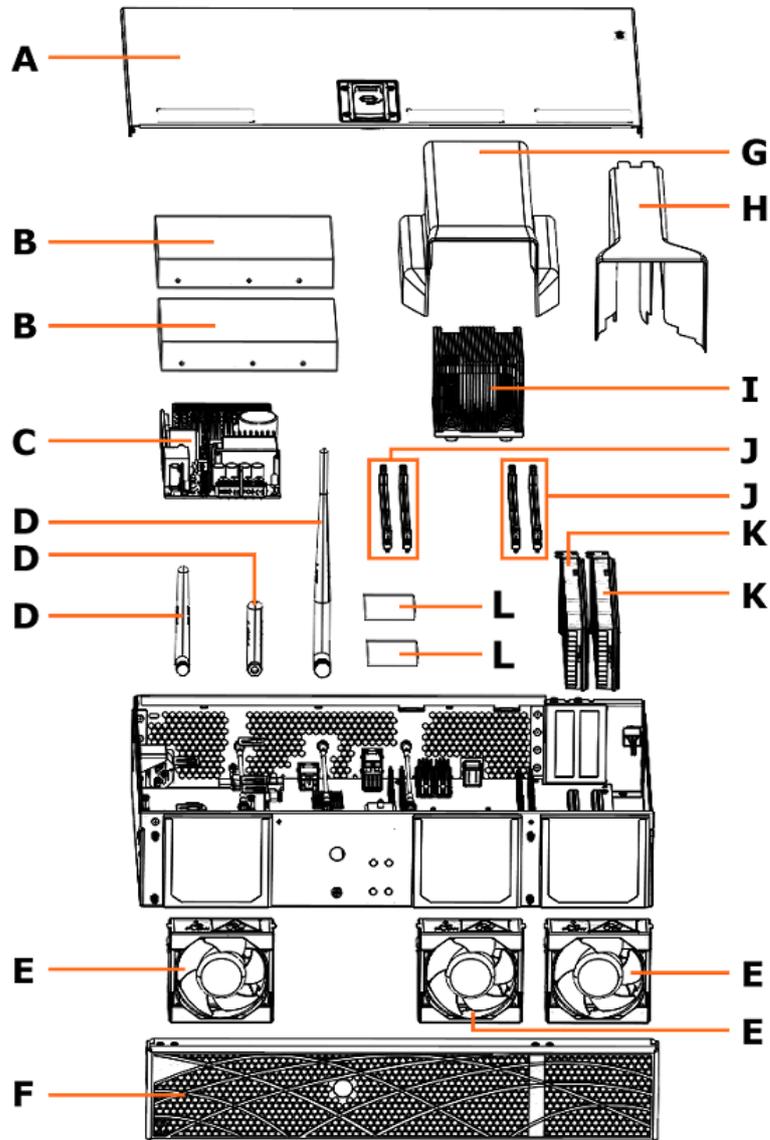
Three wireless technologies are supported:

- 2.4 GHz - 5 GHz dual-band WiFi (Dual-band WiFi)
- Long Range Wireless Area Network (LoRaWAN)
- Long Term Evolution 3G/4G Global System for Mobile Communications (LTE 3G/4G GSM)

BullSequana Edge servers are air-cooled and managed by a single Baseboard Management Controller BMC).

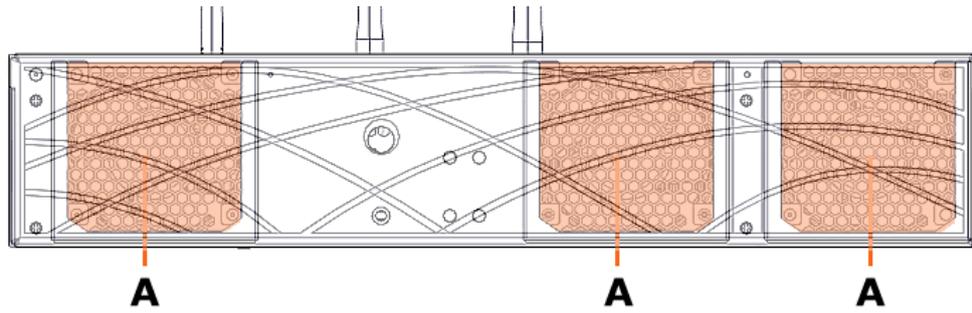
## 2.2. General description

 Exploded view



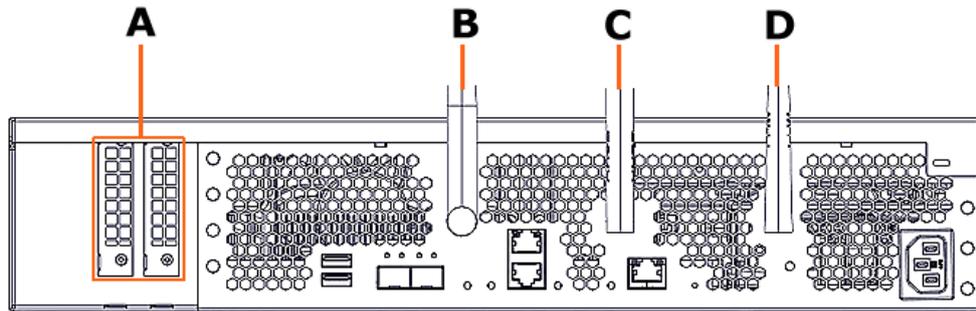
Mark	Description	Quantity
A	Top cover	1
B	Disk SATA or SDD	2
C	Power Supply Unit (PSU)	1
D	External antenna	3
E	FAN module	3
F	Bezel	1
G	Processor air duct	1
H	Accelerator air duct	1
I	Processor	1
J	Memory module	4
K	Accelerator	Up to 2
L	Mini PCIe cards	Up to 2

### 2.3. Front components



Mark	Description	Quantity
A	FAN module	3

## 2.4. Rear components

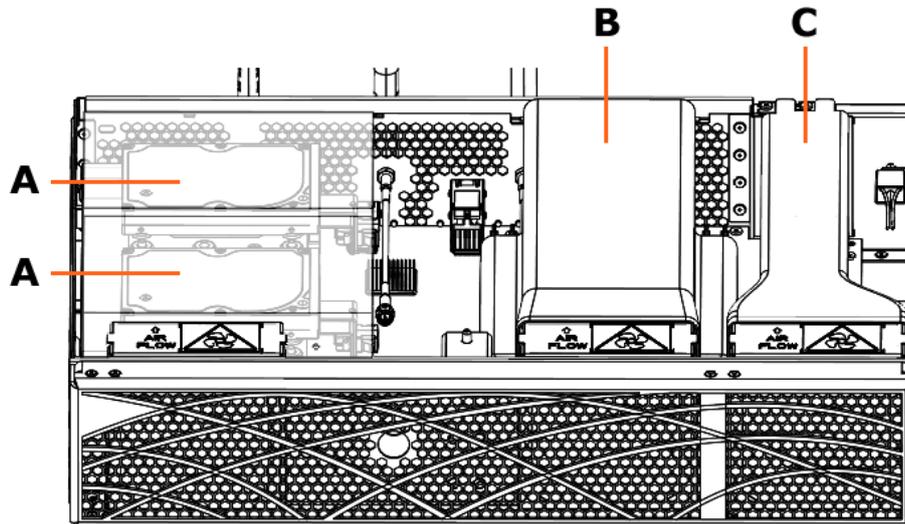


Mark	Description	Quantity
A	PCIe x16 board	2
B	External antenna 2 (Dual-band WiFi or LoRaWAN or LTE 3G/4G GSM)	1
C	External antenna 1 (Dual-band WiFi or LoRaWAN or LTE 3G/4G GSM)	1
D	External antenna 0 (BMC WiFi)	1

## 2.5. Internal components

### 2.5.1. First layer components

 Front view

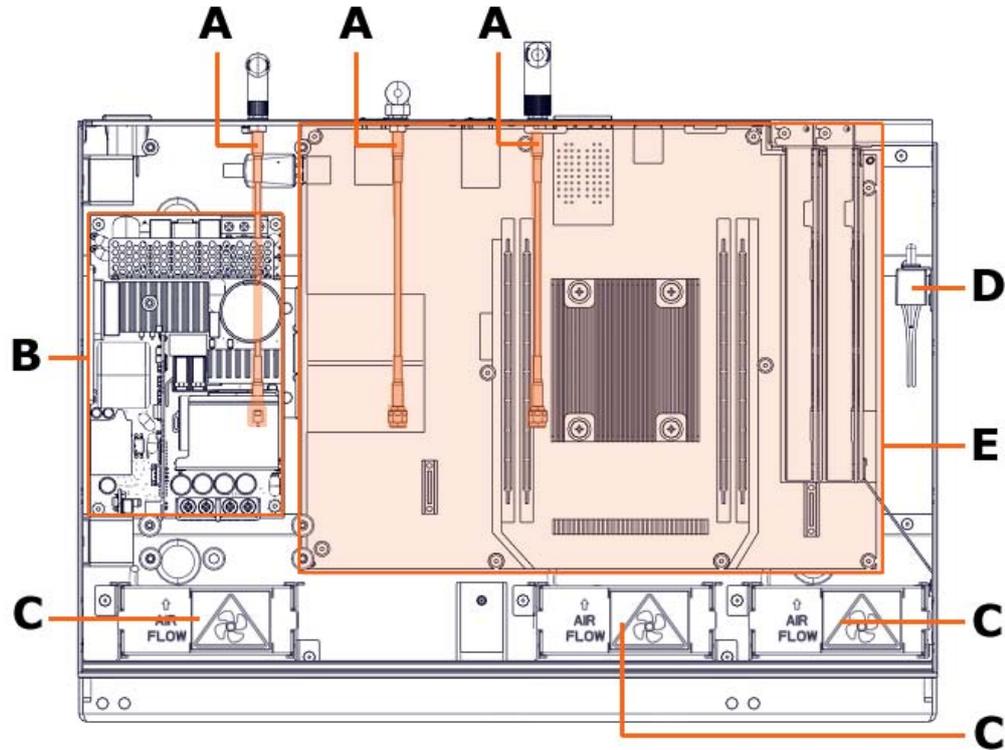


Mark	Description	Quantity
A	Disk	2
B	Processor air duct	1
C	Accelerator air duct	1

**Note** Disks assemblies and air ducts must be removed to access to the base layer components.

## 2.5.2. Base layer components

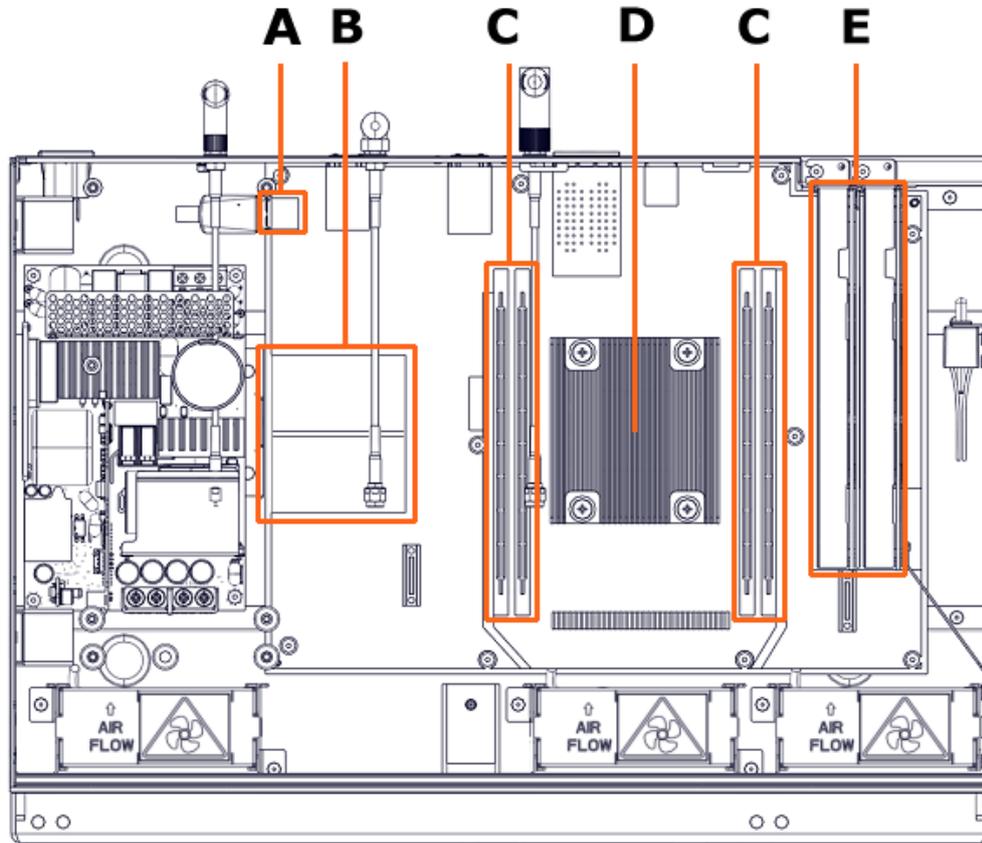
 Top view



Mark	Description	Quantity
A	Antenna connection	3
B	Power Supply Unit (PSU)	1
C	Fan	3
D	Intrusion detection switch	1
E	Motherboard	1

### 2.5.3. Motherboard

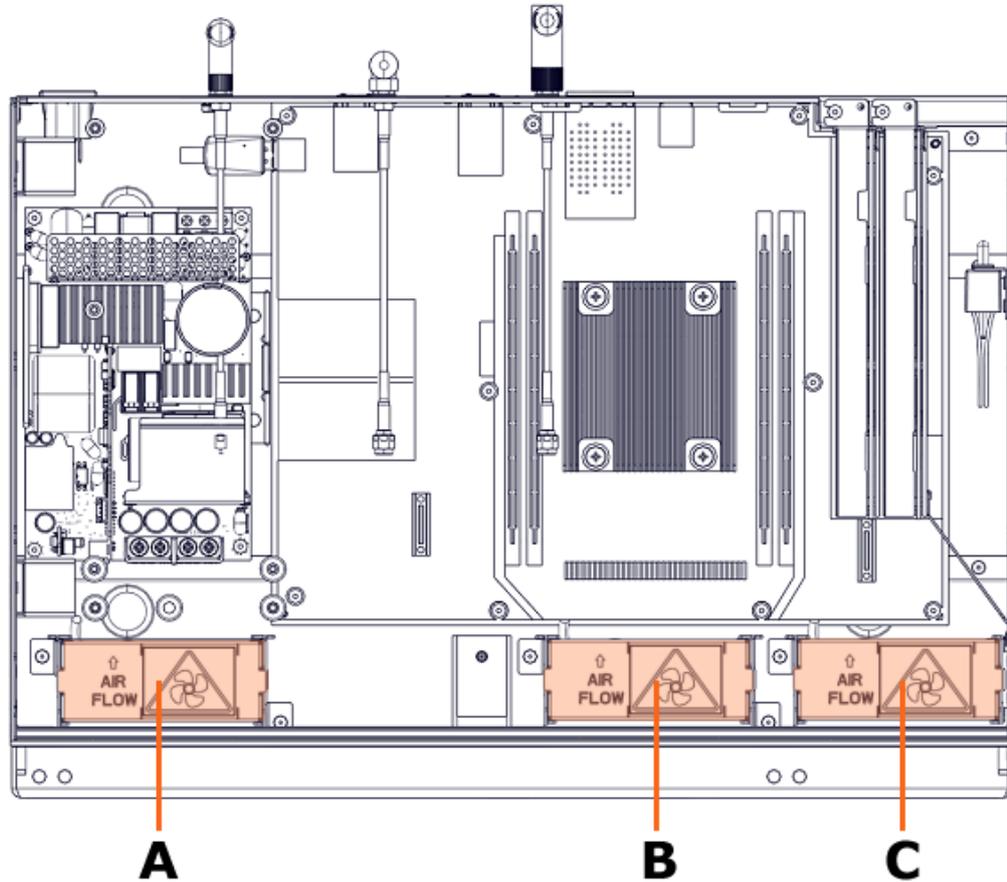
 Top view



Mark	Description	Quantity
A	USB connector (BMC WiFi dongle)	1
B	Mini PCIe slot	2
C	Memory module slot	4
D	Processor assembly	1
E	Accelerator slot	2

## 2.5.4. Fans

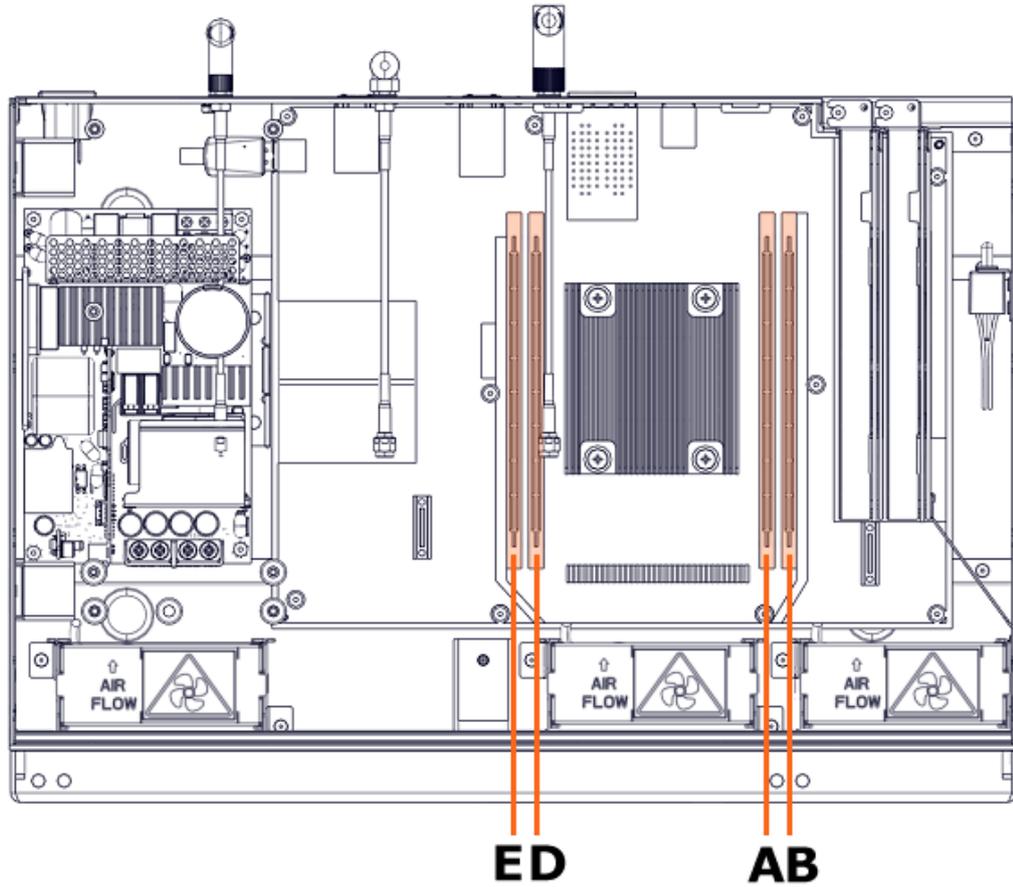
 Top view



Mark	Description
A	FAN 0_GPU
B	FAN 1_CPU
C	FAN 2_PSU

## 2.5.5. Memory modules

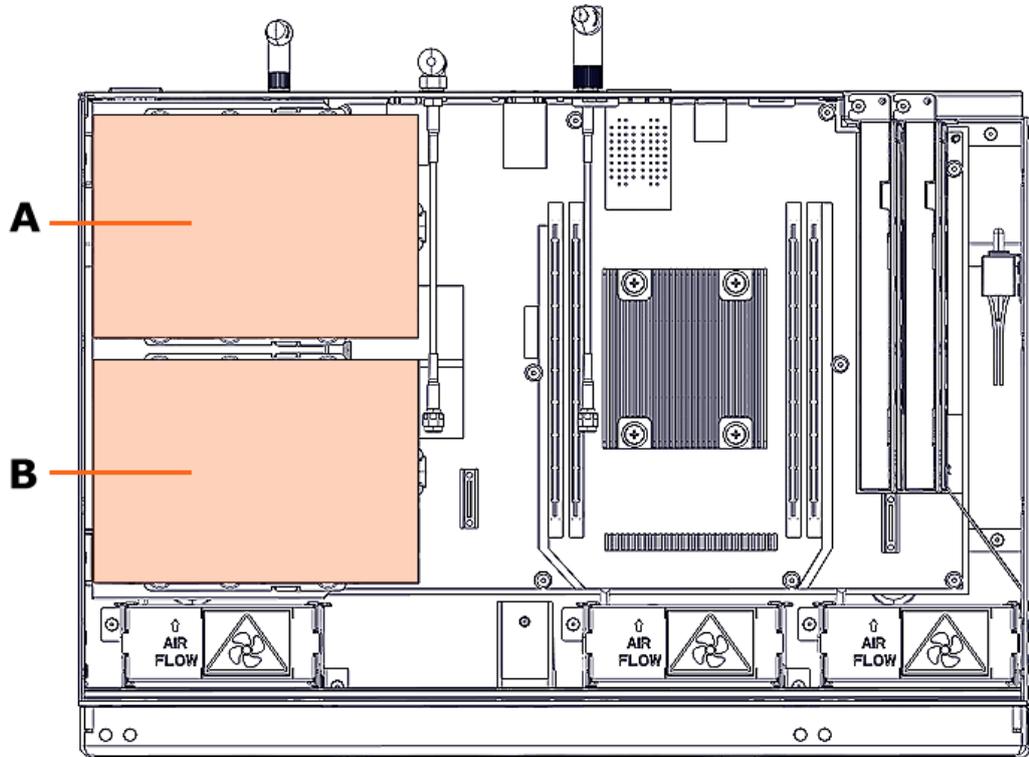
 Top view



Mark	Memory module	Channel	Board slot
A	0	0	CH-A
B	0	1	CH-B
D	0	2	CH-D
E	0	3	CH-E

## 2.5.6. Disks

 Top view

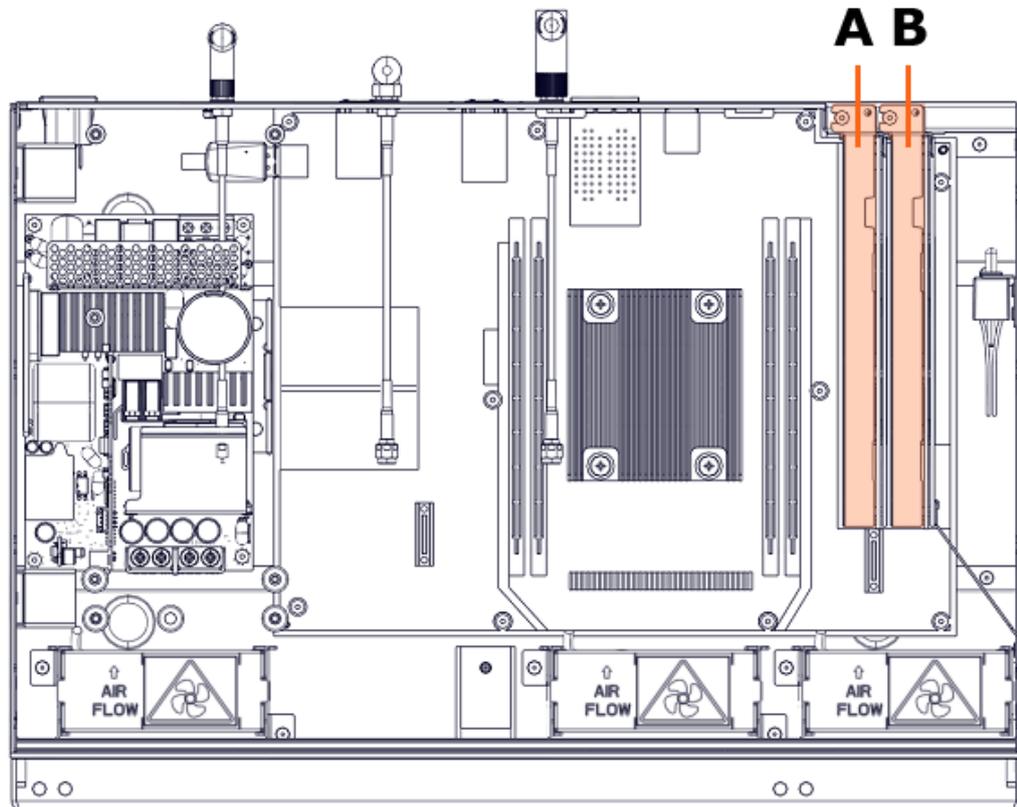


Mark	Description
A	Disk 0
B	Disk 1

## 2.5.7. Accelerator slots

### Slot numbering

 Top view



Mark	Description
A	PCIe generation 3 x16 slot 0
B	PCIe generation 3 x16 slot 1

### Options

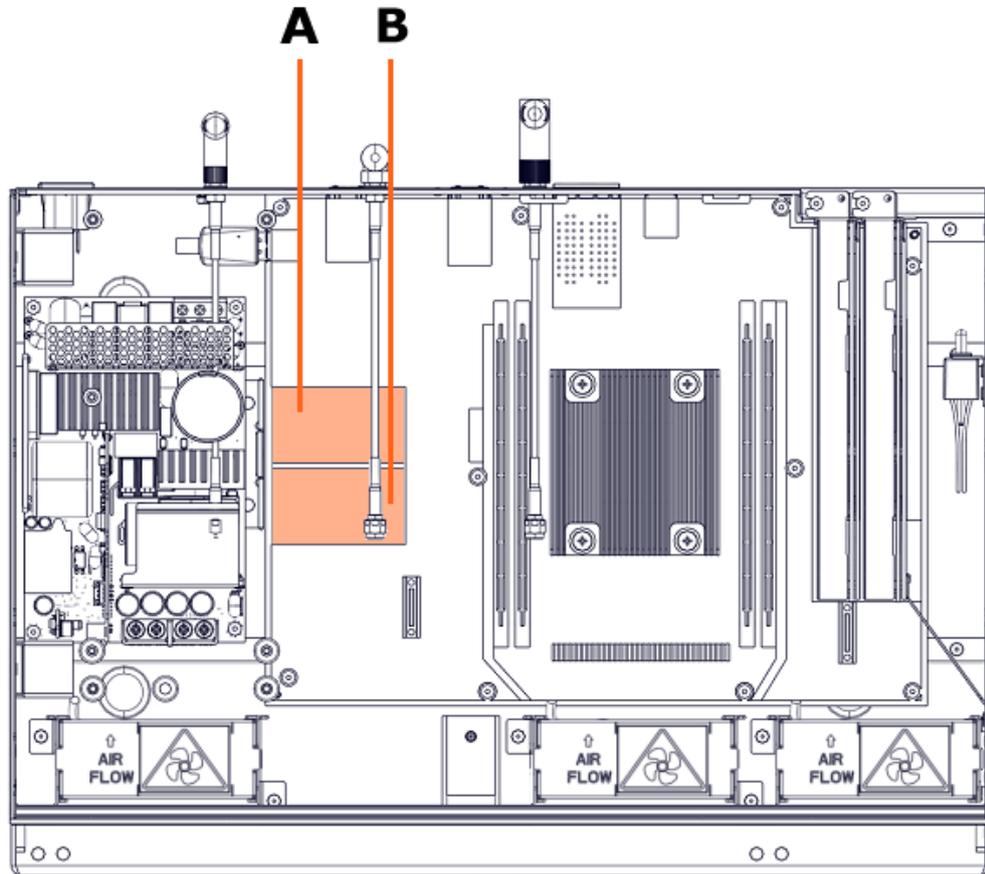
Various accelerator options are available for the PCIe slots:

- The slots are left empty
- Up to two Graphic Processing Unit (GPU) cards
- Up to one 150 watt Field Programmable Gate Array (FPGA) card
- Up to two 75 watt Field Programmable Gate Array (FPGA) cards

## 2.5.8. Mini PCIe slots

### Slot numbering

 Top view



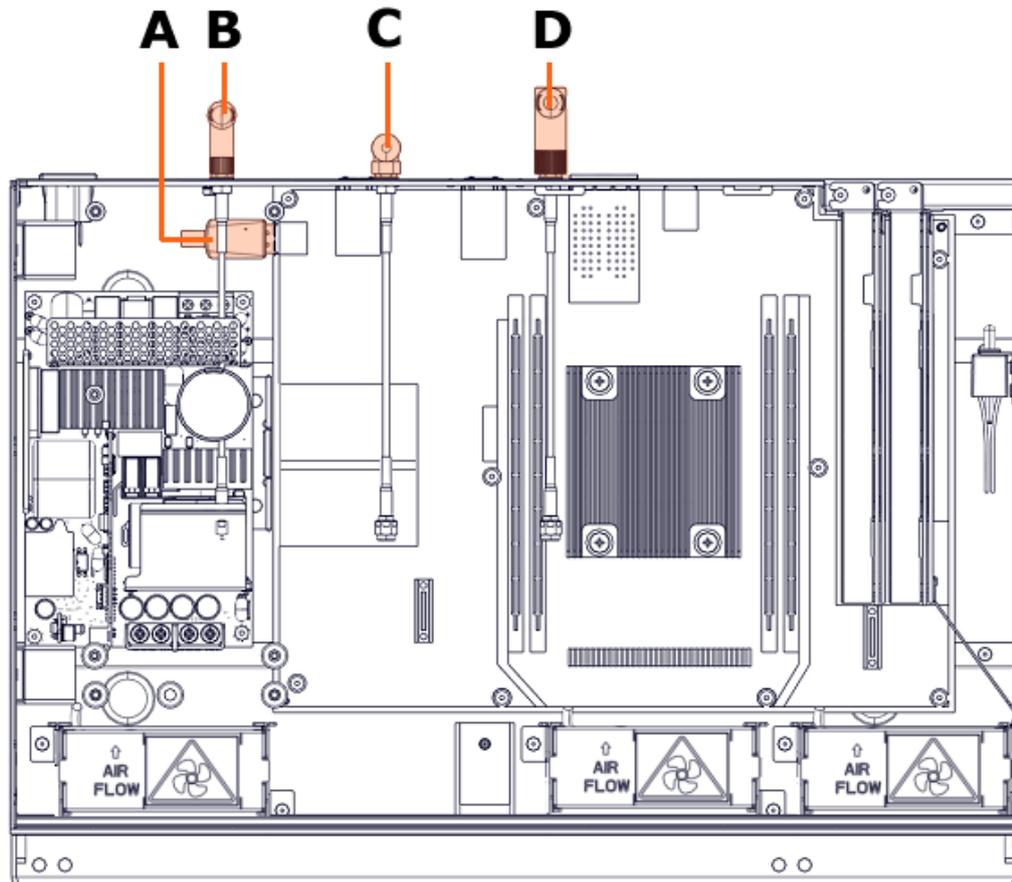
Mark	Description
A	Mini PCIe slot 0
B	Mini PCIe slot 1

### Options

The mini PCIe slots can house either dual-band WiFi or LoRaWAN or LTE 3G/4G GSM cards.

## 2.5.9. Antenna connections

 Top view



Mark	Description
A	BMC WIFI dongle
B	External antenna 0 : BMC WiFi
C	External antenna 1 : Dual-band WiFi or LoRaWAN or LTE 3G/4G GSM
D	External antenna 2 : Dual-band WiFi or LoRaWAN or LTE 3G/4G GSM

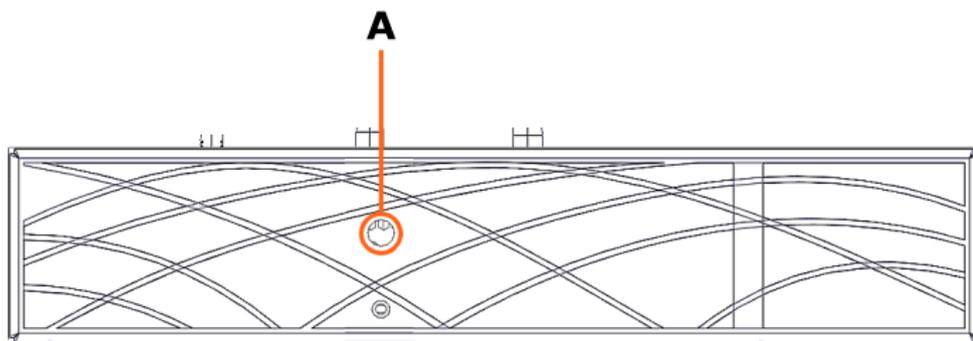


## Chapter 3. Buttons, LEDs and ports

### 3.1. Front buttons and LEDs

#### 3.1.1. Buttons

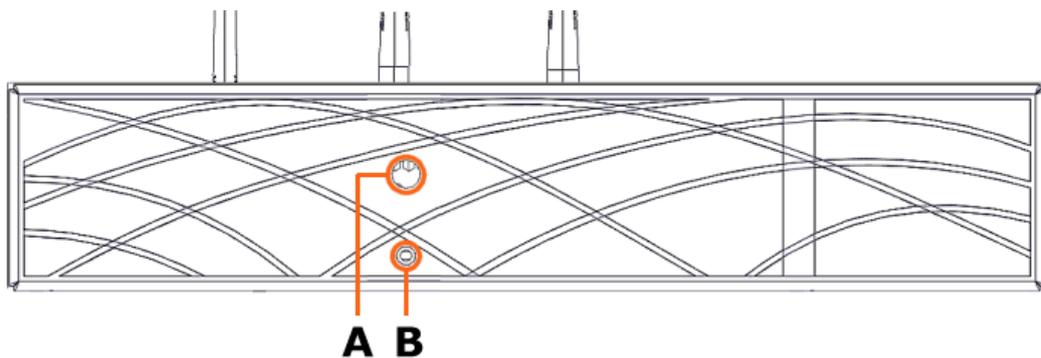
 Front view



Mark	Description
A	Power On/Off

#### 3.1.2. LEDs

 Front view

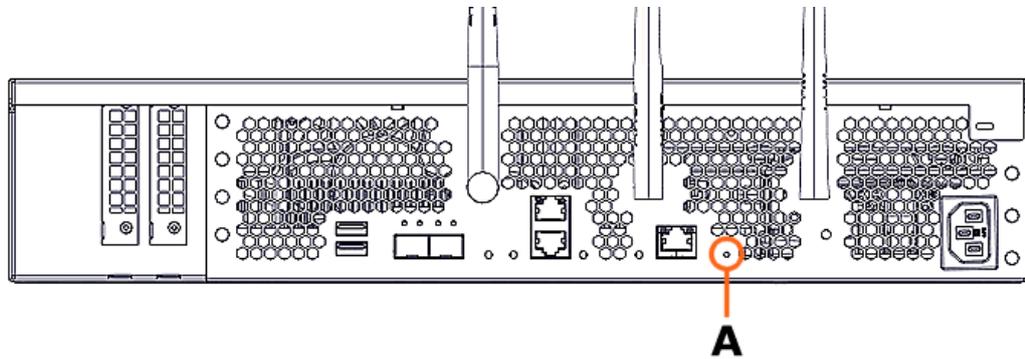


Mark	Color	Description
A	Solid green	Module power on status / OS boot
	Blinking green	Module standby status / BMC boot
B	Solid blue	Module Identification

## 3.2. Rear buttons, LEDs and ports

### 3.2.1. Buttons

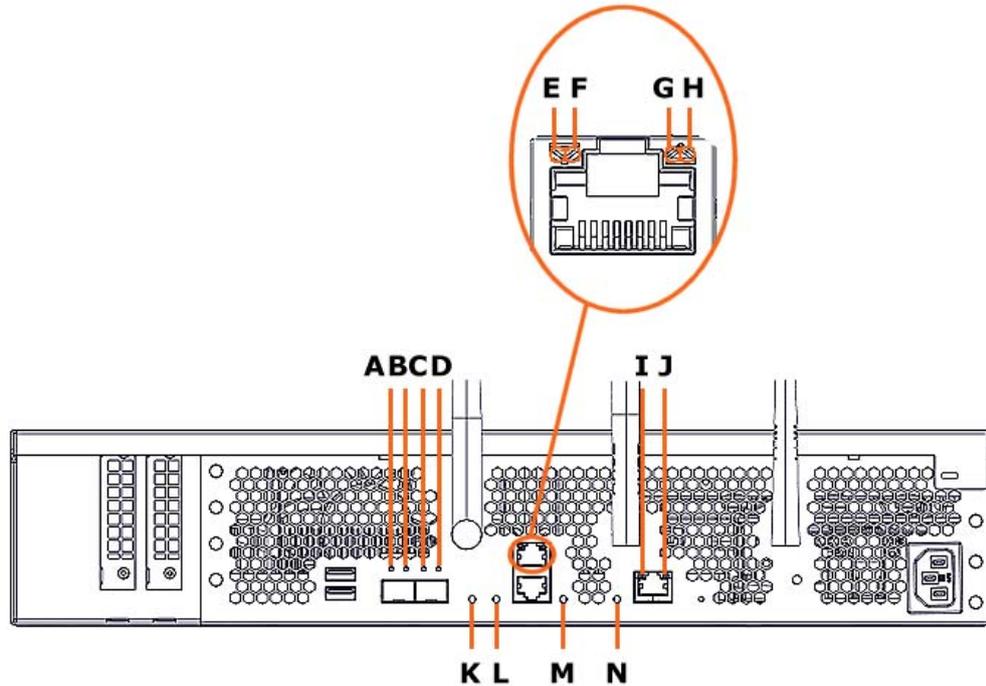
 Rear view



Mark	Description
A	Firmware recovery button

### 3.2.2. LEDs

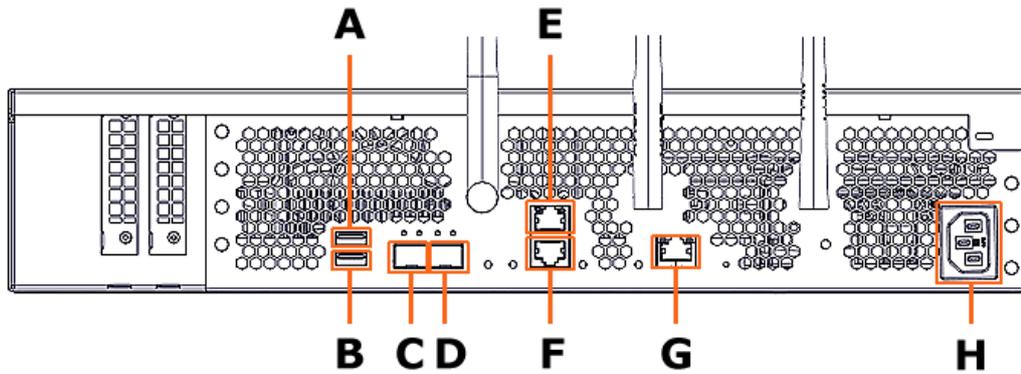
 Rear view



Mark	Color	Description	Component
A	Amber	Link 1 Gb/s Ethernet up	SFP+ port 1
	Green	Link 10 Gb/s Ethernet up	SFP+ port 1
B	Blinking amber	Ethernet link activity	SFP+ port 1
C	Amber	Link 1 Gb/s Ethernet up	SFP+ port 0
	Green	Link 10 Gb/s Ethernet up	SFP+ port 0
D	Blinking amber	Ethernet link activity	SFP+ port 0
E	Green	Link 1 Gb/s Ethernet up	RJ45 port 0
F	Blinking amber	Ethernet link activity	RJ45 port 0
G	Blinking amber	Ethernet link activity	RJ45 port 1
H	Green	Link 1 Gb/s Ethernet up	RJ45 port 1
I	Green	Link 1 Gb/s Ethernet up	RJ45 BMC
J	Blinking amber	Ethernet link activity	RJ45 BMC
K	Red	Error	N/A
L	Red	Intrusion	N/A
M	Blinking green	SATA activity	SATA 1
N	Blinking green	SATA activity	SATA 0

### 3.2.3. Ports

 Rear view



Mark	Port type	Port name
A	USB 3.0	Port 1
B	USB 3.0	Port 0
C	SFP+ - 10 Gb/s Ethernet	Port 1
D	SFP+ - 10 Gb/s Ethernet	Port 0
E	RJ45 - 1 Gb/s Ethernet	Port 1 - host
F	RJ45 - 1 Gb/s Ethernet	Port 0 - host/BMC
G	RJ45 - 1 Gb/s Ethernet	BMC
H	220V power supply	N/A

---

## Appendix A. Technical description

### A.1. General technical specifications

<b>Operating Limits</b>	
Ambient air temperature	+5°C to + 45°C Gradient 20°C / hour
Relative humidity (non condensing)	5% to 90% Gradient 5%/hour
Pressure	70 to 106 kPa
Elevation	Sea level < 3000 m
<b>Non-Operating Limits</b>	
Ambient air temperature	<-20°C and >60°C
Relative humidity (non condensing)	<5% and >95% (Gradient 30%/h)
Moisture content	1 to 29 g/m <sup>3</sup>
<b>Shipping Limits</b>	
Operating air temperature	-20°C to + 60°C Gradient 25°C/hour
Relative humidity (non condensing)	5% to 95% Gradient 30%/hour

**A.2. Dimensions and weight**

<b>BullSequana Edge</b>	
Height	2U - 86 mm
Width	430 mm
Depth	290 mm
Weight	10 Kg

### A.3. Module technical specifications

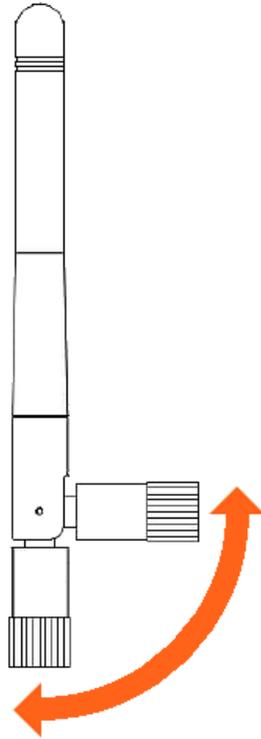
<b>Electrical Specifications</b>	
Each BullSequana Edge module is equipped with 1 PSU	
Rated Current	6 - 3 A
Power consumption	Typical: < 500 W
Thermal dissipation	Maximum: 600 W
Rated Voltage Range	100 - 240 V
Rated Frequency Range	50/60 Hz
<b>Environmental Specifications</b>	
Noise	If the temperature value at the entry of the module is 25°C, if the generated power is 75% of the TDP maximal value and without fan filter: 40dB

## A.4. Server Technical Description

<b>Processor</b>	
Number	BullSequana Edge: 1 processor
Type	Intel® Xeon® family: Skylake-D
<b>Architecture</b>	
Platform	Based on Intel Yuba City Platform
<b>Memory</b>	
Minimum / Maximum	BullSequana Edge: up to 256 GB
Type	DDR4 RDIMM, LR-DIMM Up to 2667 MT/s
Slots	4x slots per module
<b>I/O slots per module</b>	
Bus slots	2x16 Gen3 PCIe slots
<b>I/O ports per module</b>	
USB port	2 USB 3.0
Ethernet port	2x 10 GbE and 3x 1 GbE ports
<b>Disk bays per module</b>	
Disk	2x 2.5" SSD\HDD or 3.5" HDD
<b>GPUs per module</b>	
GPU	2x NVIDIA GPU cards

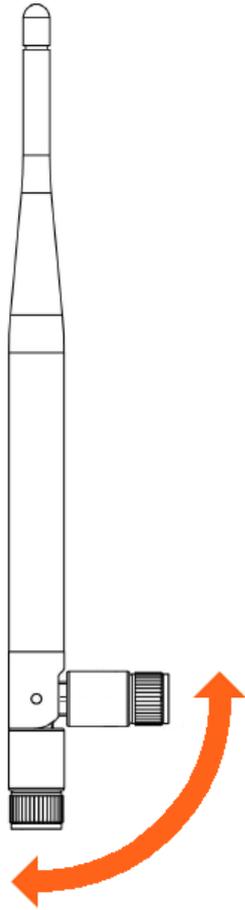
## A.5. Antenna specifications

### A.5.1. Dual-band WiFi



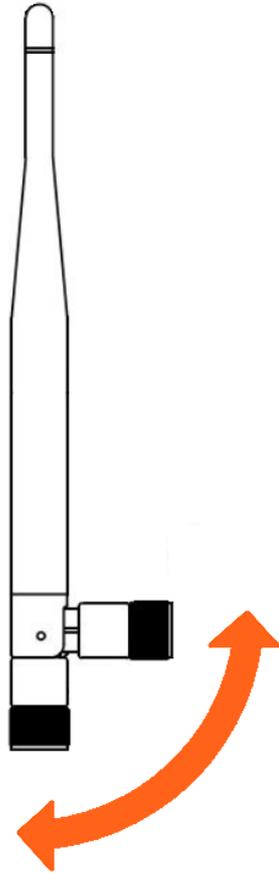
<b>Dimensions</b>	
Unfolded height	108 mm
Attached height	78 mm
Maximum width	10 mm
Minimum width	8 mm
Attached depth	31 mm
<b>Technical specifications</b>	
Frequency	2.4 - 5.8 GHz
Voltage Standing Wave Ratio	$\leq 1.8 : 1$
Gain	2.5 dB
Polarization	Vertical
Impedance	50 $\Omega$
Max Power	20W

## A.5.2. LoRaWAN



<b>Dimensions</b>	
Unfolded height	195 mm
Attached height	172 mm
Maximum width	13 mm
Minimum width	6 mm
Attached depth	38 mm
<b>Technical specifications</b>	
Frequency	868 MHz
Voltage Standing Wave Ratio	<2.0
Gain	3 dBi
Polarization	Linear
Impedance	50 $\Omega$

### A.5.3. LTE 3G/4G GSM



<b>Dimensions</b>	
Unfolded height	195 mm
Attached height	172 mm
Maximum width	13 mm
Minimum width	6 mm
Attached depth	38 mm
<b>Technical specifications</b>	
Frequency	700 - 2700 MHz
Voltage Standing Wave Ratio	$\leq 2.5$
Gain	5 dB
Polarization	Vertical
Impedance	50 $\Omega$
Max Power	50W



---

# Acronyms

---

## A

### **APIPA**

Automatic Private IP Addressing

---

## B

### **BIOS**

Basic Input / Output System

### **BMC**

Baseboard Management Controller

### **BSM**

Bull System Management software

---

## C

### **CPLD**

Complex Programmable Logic Device

### **CPU**

Central Processing Unit

### **CRU**

Customer Replaceable Unit

---

## D

### **DDR4**

Double Data Rate fourth generation

### **DHCP**

Dynamic Host Configuration Protocol

### **DIMM**

Dual In-line Memory Module

### **DIN**

Deutsches Institut für Normung

### **DNS**

Domain Name Server

---

## E

### **ESD**

Electrostatic Discharge

---

## F

### **FPGA**

Field Programmable Gate Array

### **FRU**

Field Replaceable Unit

---

## **G**

### **GPU**

Graphical Processing Unit

### **GSM**

Global System for Mobile Communications

---

## **H**

### **HDD**

Hard Disk Drive

### **HTTPS**

HyperText Transfer Protocol Secure

---

## **I**

### **IP**

Internet Protocol

### **IPMI**

Intelligent Platform Management Interface

---

## **J**

No entries.

---

## **K**

### **KVM**

Keyboard Video Mouse

---

## **L**

### **LAN**

Local Area Network

### **LED**

Light Emitting Diode

### **LLD**

Low Level Discovery

### **LoRa**

Long Range wireless communications

### **LoRaWAN**

Long Range Wide Area Network

### **LR-DIMM**

Load Reduced Dual In-line Memory Module

### **LTE**

Long Term Evolution

---

## M

### MAC

Media Access Control

### MI

Machine Intelligence

### MISM

Machine Intelligence System Management

### MIPSE

Machine Intelligence Pocket Server

---

## N

### NTP

Network Time Protocol

---

## O

### OOB

Out of Band

---

## P

### PCI

Peripheral Component Interconnect

### PCIe

PCI Express

### PDU

Power Distribution Unit

### PSK

Pre-shared Key

### PSU

Power Supply Unit

### PXE

Preboot execution Environment (PXE)

---

## Q

No entries.

---

## R

### RDIMM

Registered Dual In-line Memory Module

### REST

Representational State Transfer

---

## S

### **SATA**

Serial ATA

### **SEL**

System Event Log

### **SFP**

Small Form-factor Pluggable

### **SHC**

Server Hardware Console

### **SOL**

Serial Over LAN

### **SSD**

Solid State Drive

### **SMTP**

Simple Mail Transfer Protocol

### **SMS**

Short Message Service

### **SSH**

Secured Shell

### **SSL**

Secure Socket Layer

---

## T

### **TDP**

Thermal Design Point

### **TFTP**

Trivial File Transfer Protocol

### **TSL**

Transport Layer Security

---

## U

### **USB**

Universal Serial Bus

### **UTC**

Universal Time Coordinated

---

## V

### **VESA**

Video Electronics Standard Association

---

## W

### **WIFI**

Wireless Fidelity

---

**X**

No entries.

---

**Y**

No entries.

---

**Z**

No entries.





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